izmo

June 10, 2026

The Manager Corporate Relationship Department **BSE Limited** Floor 25, Phiroze Jeejeebhoy Tower Dalal Street, Mumbai-400001	The Manager – Listing Department **National Stock Exchange of India Limited** Exchange Plaza, 5th Floor Plot No. C/1, G Block, Bandra Kurla Complex, Bandra(E), Mumbai-400051
BSE Scrip Code: **532341**	NSE Symbol: **IZMO**

Dear Sir/Madam,

Subject: izmo Corporate Presentation

In terms of Regulation 30 of the SEBI (Listing Obligations and Disclosure Requirements) Regulations, 2015, we are enclosing herewith the "izmo Corporate Presentation".

Further a copy of the same is also available on the website of the Company, viz., ***www.izmoltd.com***

Kindly take the same on record.

Thanking You

Yours faithfully,
for **IZMO Limited**

VARUN KUMAR SRIDHARA ADGUR
Digitally signed by VARUN KUMAR SRIDHARA ADGUR
Date: 2026.06.10 18:49:01 +05'30'

Varun Kumar A S
Company Secretary and Compliance Officer

Enc: As Above

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● CORPORATE PRESENTATION

izmo Ltd.

Digital + Semiconductor

Hi-Tech growth story – SaaS to Semiconductors

LISTED · izmoltd.com · izmomicro.com

Bengaluru · San Francisco · Chicago · Paris · Brussels · Cologne · London

EXECUTIVE SUMMARY

Two Engines, One Capital-Efficient Story

DIGITAL

SaaS Cashflow Engine

- izmocars · izmostock · izmoemporio
- FrogData — DEEP AI for dealerships
- 3,000+ dealers across 22 countries
- 1,000+ FrogData deployments

SEMICONDUCTOR

izmomicro - Growth Engine

Design+ Advanced Packaging + Silicon Photonics

Proven track record · India's first integrated SiPh facility

Optical Transceivers

Adjacent expansion · Same plant, incremental tooling

ABOUT IZMO LTD

Public Indian Group, Global Footprint, 30-Year Track Record

Founded 1995.
Listed on the National Stock Exchange and Bombay Stock Exchange of India. Headquartered in Bengaluru with operating offices and customers in North America, Europe and Asia.

Digital / SaaS

- izmocars
- izmostock
- izmoemporio

+ FrogData AI for dealerships

Semiconductor

izmo Microsystems

- Design+ ATMP
- Silicon Photonics
- Optical Transceivers

30+
Years Operating History

6
Global Offices

3,000+
Automotive OEM & Dealer Customers

Semicon
+ Defence + Space + Export · Semiconductor

GLOBAL
San Francisco · Chicago · Paris · Brussels · Cologne · London · Bengaluru

CORPORATE EVOLUTION

From Auto-Retail Software to Semiconductors

1995

Founded

izmo Ltd established

2000s

US Setup

United States operations; izmocars launched globally

2014

European Expansion

Offices opened across European markets

2018

FrogData Launched

AI/analytics platform for US dealerships

2020

Worldwide Presence

Customers across 22 countries; 3,000+ dealers

2022

izmo Microsystems

Subsidiary formed — diversification into semiconductors

2026

Capacity Expansion

Integrated SiPh line + optical transceiver adjacency

Three decades of public-company discipline and a deliberate, well-executed diversification from software into semiconductors.

STRATEGIC ARCHITECTURE

Two Divisions — Semiconductor as Growth Engine

izmoltd.

Listed in BSE and NSE

Digital

Auto-retail SaaS + dealership AI

- izmocars · izmoauto · izmostock
- izmoemporio (3D showroom)
- FrogData DEEP AI platform

3,000+	22	1,000+
Dealers	Countries	FrogData Customers

STABLE BASE BUSINESS

Semiconductor

izmo Microsystems — Design+ ATMP

- Advanced Packaging (proven)
- Silicon Photonics (integrated line)
- Optical Transceivers (adjacent)

10+ Years	Defence	IMEC · ISRO
Delivery record	+ Space + Export	Partners

GROWTH ENGINE

● DIGITAL - IZMOCARS

Auto-Retail Platform Suite for Global Dealers

izmocars is a comprehensive digital platform serving automotive OEMs and dealers across 28 countries. Three distinct product lines address web presence, inventory imaging, and immersive retail experiences.

izmoauto

DIGITAL PLATFORM SUITE

- International digital web & marketing platform for OEMs & dealers
- Parts CRM for OEMs
- FleetVelocity solution for leasing & fleet operators

izmostock

VEHICLE IMAGING

- World's largest automotive image library — 2M+ images
- Powers ~70% of global rental-car listings
- <3% annual customer churn

izmoemporio

3D VIRTUAL SHOWROOM

- Immersive online showroom for OEMs and dealers
- Configurator + 360° model rendering
- Growing OEM deployments

Transformational AI Solutions for US Dealerships

FrogData is a next-generation DEEP AI platform purpose-built for automotive dealerships — combining predictive analytics, operational intelligence, and hyperlocal marketing in a unified suite.

FrogData AI - Predictive

Predictive analytics across inventory, F&I, and service operations - pricing, demand forecasting, and lead scoring powered by deep machine learning models trained on dealership data.

FixedOps Mojo - Operations

AI-driven operations management platform optimizing the service department - scheduling, throughput, parts usage, and advisor productivity through intelligent workflow automation.

FixedOps Velocity - Marketing

Hyperlocal marketing for fixed operations powered by intelligent AI - targeting the right customer with the right service offer at the right moment to drive retention and revenue.

● AI DEVELOPMENT ENGINE

Powering the Next Generation of Dealer Products

An internal AI engine drives every new FrogData product. Two proprietary capabilities reduce time-to-market for new AI features and create a defensible build-velocity advantage in the dealership software market.

CONTINUOUS LEARNING LOOP

AI Pulse

A real-time signal layer that continuously ingests dealership operating data, surfaces emerging patterns, and feeds them back into model retraining.

- Always-on data pulse across 200+ live deployments
- Detects market shifts, drift, and new behavioural patterns
- Closes the loop from production data back to model updates

AUTONOMOUS WORKFLOWS

Agentic Automation

AI agents that act inside the dealer workflow pricing, follow-up, scheduling, parts management with human policy guardrails.

- Multi-step agents triggered by real-time pulse signals
- Operates inside dealer software with audit trails
- Drives operational productivity beyond traditional analytics

● DIGITAL BUSINESS

Stable Cashflow Engine Funding Semiconductor Growth

A profitable, predictable SaaS base. Long-tenured customers, low churn, recurring licence and subscription revenue. The Digital business is the funding base that lets izmo Ltd. invest in semiconductor capacity expansion in a measured, capital-efficient way.

Recurring Revenue

Multi-year SaaS contracts with global dealer customers; <3% churn at izmostock.

Capital Discipline

Cash generation reduces external funding need and protects against excessive shareholder dilution during semiconductor scale-up.

Customer Stickiness

3,000+ dealers and 1,000+ FrogData customers, with low churn.

PART II

Semiconductor

The Growth Engine

Advanced Packaging · Silicon Photonics · Optical Transceivers

CAPABILITIES

- Multi-die assembly
- Sub-µm alignment
- mmWave RF
- Photonic packaging

Design+ ATMP - Specialty Packaging Services

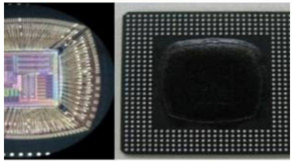
POSITIONING

Design+ ATMP

Well positioned for high-complexity, mid-volume, high-value packaging and module manufacturing — work that commodity OSAT and board-assembly EMS cannot serve.

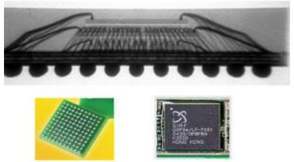
CUSTOMER FOCUS

Defence	Space	Industrial
BEL · HAL · NPOL	ISRO · SAC · SCL	Automotive . EV. Power



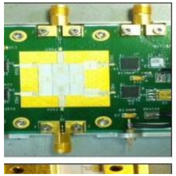
Advanced Packaging

BGA · TBGA · SiP



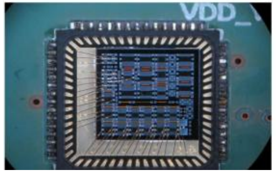
SiP / Sensor Modules

Multi-die integration



RF / MMIC Modules

Up to 100 GHz



Photonics / MEMS

Precision alignment

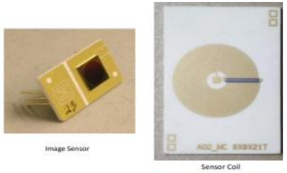
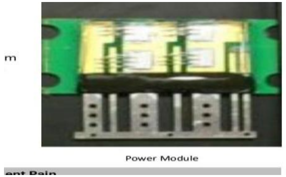


Image Sensors

CMOS / CCD assembly

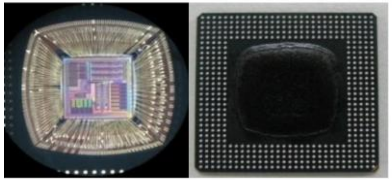


Power Electronics, GaN

Power module assembly

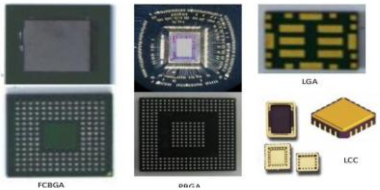
PRODUCT SHOWCASE

Advanced Packaging — Design + Manufacturing Capability



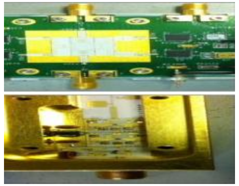
500-ball Wire-Bond TBGA

3-tier stacked die, multi-chip



BGA / FCBGA / LGA

Multi-tier wire bonding, BT substrate



100 GHz RF Amplifier

mmWave MMIC, GaAs die, ribbon bond

MIC Assembly

Mixed-board, MMIC, radar systems

More image from Nitin to add.

HMC Space Module

Hybrid microcircuit, 24-switch

SiP Other Products

Field-replaceable controller modules

Cochlear Implant

Medical-grade biocompatible

Power Module

H-Bridge MOSFET, 40A continuous

Recent customer engagements include BEL multi-unit, ISRO/SAC, defence labs, and European photonics/sensor leaders (Bosch, Cologne Chip, Lionix, Caeleste, IMEC IC-link) — alongside an established base of historical customers.

SILICON PHOTONICS TODAY

A Fragmented Packaging Workflow Across Multiple Vendors

Globally fragmented. SiPh module assembly today is split across 2-3 separate specialist vendors - fibre attach, die attach and test typically live in different facilities. Long lead times, multiple shipments, yield loss at hand-offs.

VENDOR A

STEP 1

Wafer Sort

PIC singulation, sort, taping

VENDOR A

STEP 2

Die Attach

PIC + driver IC bonding

VENDOR B

STEP 3

Fibre Alignment

Active alignment, attach, sealing

VENDOR B

STEP 4

Wire Bonding

High-speed bonds, RF interconnects

VENDOR C

STEP 5

Test + Burn-In

Optical/RF/reliability validation

CONSEQUENCES OF FRAGMENTATION

12-20 weeks
Cumulative cycle time

Yield loss
At every vendor hand-off

IP exposure
Across multiple parties

Logistics cost
Repeated shipping & QC

OUR SOLUTION

India's First Integrated Silicon Photonics Packaging Line

✓ **One roof. Five integrated stages.** All five SiPh packaging stages on a single line — design, alignment, bonding and test integrated in-house, with proprietary process IP co-developed with CPPICS / IIT Madras.

1. **Advanced Design**
   Co-design with customer
2. **MCM Integration**
   Multi-die/multi-tech
3. **Precision Fibre Alignment**
   ±0.1 µm tolerance
4. **Specialised Wire Bonding**
   Au/Al, fine pitch, ribbon
5. **Comprehensive Testing**
   DC/RF/optical/reliability

50% faster time-to-market · **30-50%** first-pass yield · **15-25% lower** development cost

TECHNOLOGY MOAT

izmo Core Technology — Built Over a Decade

The moat is not a single partnership. It is the compounded effect of a decade of specialty packaging delivery — process know-how, supply-chain depth, methodology and yield discipline that cannot be acquired by capex alone.

EXPERIENCE

Decade of Delivery

Multi-die, RF, MEMS, photonics – complex packaging delivered into industry, defence, space over 10+ years.

KNOW-HOW

Process Recipes

Proprietary process recipes for wedge / ribbon bonding, sub-micron alignment, thermal management at 4-5W in 1 sq inch.

SUPPLY CHAIN

Qualified Vendor Base

Years of supplier qualification for substrates, lids, special chemicals - supply assurance built before competition.

METHODOLOGY

Design+ ATMP

Engagement model that brings packaging engineering into the customer's design cycle - drives margin and stickiness.

RELIABILITY

Qualified at Customer

Already on production lines at BEL, ISRO, EU customers - qualification cycles already absorbed, not to be re-run.

YIELD

First-Pass Discipline

30-50% improvement in first-pass yield benchmarks — the metric that separates specialty from commodity.

Strategic SiPh partnerships (IMEC IC-link, ISRO/SAC, Lionix International, CPPICS/IIT Madras) extend this moat into next-generation photonics.

POLICY & ECOSYSTEM ALIGNMENT

Aligned with India's National Semiconductor Priority

izmo Microsystems' integrated SiPh line is strategically aligned with India's national semiconductor agenda. Indigenous SiPh and packaging capability is a strategic imperative - and izmo is positioned to be a direct beneficiary across policy, procurement, and deep-tech partnerships.

NATIONAL PRIORITY

Make in India

- Indigenous SiPh + packaging capability — strategic for the country
- Eligible for Class-I Local Supplier status under public procurement rules
- Domestic sourcing mandate creates protected demand for government RFPs

ISM (MEITY)

~$10 Billion MEITY Programme

- MEITY-driven scheme to build India's chip + display fab ecosystem
- Includes fab, ATMP and design-linked incentive components
- Strong demand pull for domestic specialty packaging partners

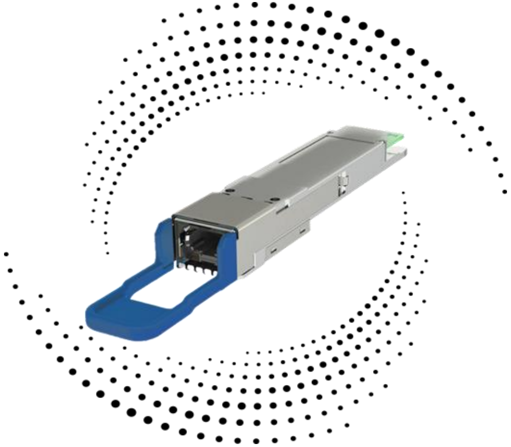
CPPICS / IIT MADRAS

National Photonics IC Research Centre

- MEITY-funded national centre for photonic IC research
- Co-development of SiPh process technology with izmo Microsystems
- Bridges academic photonics research to commercial deployment

● STRATEGIC EXPANSION

Optical Transceivers -Adjacent Upside, Same Plant



PRODUCT ROADMAP

400G-DR4	800G-DR8	1.6T-DR8
Pilot - FY28	Primary - FY28-30	Future - FY30+
SECONDARY	PRIMARY PRODUCT	ROADMAP

Why Now

Hyperscaler 400G/800G deployment ramping in India; datacom growth ~45% YoY. The window is open for new domestic supply.

Why Us

Silicon Photonics packaging line being built anyway; transceiver assembly is incremental tooling on the same plant.

Why India

Make in India compliance unlocks government RFPs that imported transceivers cannot serve. Class-I Local Supplier targeted.

MARKET DRIVER

The AI Boom Runs on High-Speed Optical Interconnects

AI INFRASTRUCTURE

The Real Bottleneck

AI training and inference clusters move terabytes of data between GPUs every second. Copper interconnects have hit their physical ceiling.

Silicon photonics is the only viable path to the bandwidth, density and power efficiency the next AI generation requires.

INDIA DATA CENTER BOOM

$13B+	India data center capex committed by hyperscalers and COLO operators
~3 GW	New data center capacity in India by 2028 (vs ~1 GW in 2024)
45% YoY	Datacom transceiver demand growth, driven by AI cluster build-outs

OUR POSITIONING

AI Infrastructure Build Out - Key Driver

Large TAM with AI tailwind. Both Advanced Packaging + SiPh and Optical Transceivers benefit directly from the same demand driver - AI infrastructure build-out at hyperscalers and Indian colocation operators.

Advanced Packaging + Silicon Photonics

$50B → $80B

Advanced Packaging by 2030 (8-10% CAGR)

$2-3B → $10B+

Silicon Photonics by 2030 (25-30% CAGR)

- Heterogeneous integration is the only path past copper limits
- AI accelerators driving chiplet + co-packaged optics demand
- India SiPh capacity essentially zero - first-mover advantage

Optical Transceivers

$13.5B → $28B

Global transceivers by 2030 (~14% CAGR)

$600M+

Projected India market > 30% CAGR

- AI cluster fabric is largely 400G/800G optical
- Domestic data center boom creates protected demand
- Make in India regulation creates buyer mandate

COMPETITIVE POSITIONING

What Makes izmo Hard to Replicate

Years of process delivery, customer qualification cycles, and design-engagement know-how that compounds.

izmo Microsystems
Unique Strengths

- Shipping SiPh packages since 2014 — 10+ yrs of production data.
- Qualified by BEL, ISRO, EU defence primes, and industrial OEMs.
- 50,000+ units delivered across telecom, LiDAR, and sensing.
- ±0.1 µm active alignment proven in production, with custom fixturing and vision systems built in-house.
- MIL-STD-883 and ESCC-equivalent screening in production; approved vendor for BEL, DRDO, and EU defence primes.

Large EMS/OSAT
Key Limitations

- No experience with photonic die, fibre pigtails, or hermetic seal; CapEx optimised for wafer-level scale, not unit-level photonics.
- Follows customer-supplied package drawings - zero design IP; no optical or photonic simulation capability in-house.
- 3–5 yr timeline to develop or license photonics assembly processes; no recipes for low-stress die-attach on InP, $LiNbO_3$, or SiN.
- Standard pick-and-place accuracy: ±25 µm — 250× too coarse for photonics; new alignment platforms require $2–5M investment.
- Each customer requires 18–24 mo. qualification from scratch; izmo's approvals represent 8+ yrs of accumulated qual. capital.

COMPETITIVE POSITIONING

What Makes izmo Hard to Replicate

What stops a well-capitalised EMS or OSAT group from entering this space? The honest answer: capital does not create specialty packaging capability. What does is years of process delivery, customer qualification cycles, and design-engagement know-how that compounds.

izmo Microsystems DESIGN + ATMP	**Large EMS / OSAT** BOARD ASSEMBLY / HIGH VOLUME
Decade-long delivery BEL, Industrial, Defence, ISRO, EU - qualified by diverse customers	**No specialty packaging history** Built for board assembly and volume IC packaging
Co-design engagement Engineering into customer's design cycle	**Build-to-print model** Reference packages, no co-design
Process tech + deep-tech access izmo-developed process; CPPICS / IIT Madras partnership for deep tech	**No SiPh process IP** Would need to license or develop from scratch
Sub-µm fibre alignment ±0.1 µm proven on production	**Sub-µm alignment not in scope** Different tooling and discipline
EU + Defence qualifications Qualification cycles already absorbed	**Multi-year customer qualification** New entrant must restart every customer cycle

MANAGEMENT

Founders Plus Deep Technical Leadership

Sanjay Soni

Managing Director
izmo Ltd

IIM-Bangalore. Group strategy, capital markets and corporate finance.

Tej Soni

Chief Executive Officer

30+ years across automotive, software and semiconductors. Founder.

Dinanath Soni

Executive Director

Technical Visionary with 30+ years of semiconductor business experience

Nitin Ghodgaonkar

CTO / Sr. VP,
izmo Microsystems

M.Tech IIT Kharagpur with 30+ years experience in semiconductor packaging. Recognized expert in the field

Sarbashish Bhattacharjee

CTO, izmo Ltd

Over 25 years of varied experience in Application Development Project platforms, Cloud Computing, Product Design, Project Management and Deployment, Data Architecture, etc.

Chris Dulla

VP, FrogData

Sales and product leadership across the US dealership market.

STRATEGIC
ADVANTAGES

The Future of izmo Ltd.

A strategic synergy — proven cashflow engine, durable semiconductor moat, and exposure to the AI infrastructure build-out.

izmoltd.com · izmomicro.com

Dual-Engine Model

Digital SaaS funds Semiconductor expansion - not a single-bet story.

Proven, Not Promised

Decade of specialty packaging delivery to BEL, ISRO, EU customers.

Genuine Moat

Methodology + qualification + IP — compounded over 10+ years, hard to replicate.

AI Tailwind

Beneficiary of AI infrastructure build-out through SiPh and transceivers.

De-risked Capex

Same plant serves AP + SiPh + Optical Transceivers

Strategic Partners

IMEC, ISRO, Lionix, CPPICS/IITM, DustPhotonics — anchor partnerships for the SiPh roadmap.

THANK YOU!

Caution Concerning Forward- Looking Statements

Certain statements in this document may be forward-looking statements. Such forward-looking statements are subject to certain risks and uncertainties like regulatory changes, local political or economic developments, and many other factors that could cause our actual results to differ materially from those contemplated by the relevant forward-looking statements. Further, past performance is not necessarily indicative of future results. Given these risks, uncertainties and other risk factors, viewers are cautioned not to place undue reliance on these forward-looking statements. The Company will not be in any way responsible for any action taken based on such statements and undertakes no obligation to publicly update these forward-looking statements to reflect subsequent events or circumstances.